

**AMENDMENTS TO THE CLAIMS**

1. (Previously Presented) A package for a rectangular integrated circuit, comprising:

a frame having a top surface and a bottom surface, said bottom surface including an indented area where a thickness between the top surface and the bottom surface is thinner than in a non indented area of said bottom surface, said indented area sized to accept a rectangular integrated circuit; and

a contact portion, said contact portion extending along said bottom surface within said indented area, and along said bottom surface within said non indented area, said contact portion being adapted to connect to said rectangular integrated circuit at an edge thereof.

2. (Original) A package as in claim 1, wherein said package includes a connection portion, adapted for soldering to said integrated circuit.

3. (Original) A package as in claim 2, wherein said integrated circuit includes an image sensor, and a central portion of said frame defines a portion where image light can enter said image sensor.

4. (Previously Presented) A package as in claim 1, further comprising an element which allows sealing said integrated circuit relative to an environment of said package.

5. (Original) A package as in claim 3, further comprising a clear sealing element which allows sealing said integrated circuit relative to the environment.

6. (Original) A package as in claim 5, wherein said clear sealing element includes a glass lid.

7. (Original) A package as in claim 4, wherein said sealing element includes a lid portion on a top of the die and a backing portion on a rear portion of the die.

8. (Original) A package as in claim 7, wherein said indented area includes two separate sized indented areas, one sized to receive said die, and another sized to receive said backing portion.

9. (Original) A package as in claim 5, further comprising an element which protects said sealing element against damage.

10. (Original) A package as in claim 9, wherein said element which protects includes an extending part which extends above a top of said sealing element.

11. (Original) A package as in claim 3, further comprising an upper portion on said package, having surfaces adapted to accept a lens therein.

12. (Original) A package as in claim 11, wherein said surfaces include screw threads.

13. (Previously Presented) A package for an integrated circuit, comprising:  
a packaging portion having a first bottom surface with an outer perimeter and an inner perimeter, said inner perimeter being disposed at an intersection of said first bottom surface with an inward facing surface, said packaging portion having a second bottom surface within said inner perimeter, said first bottom surface, said inward facing surface, and said second bottom surface mutually having a metal contact thereon, said metal contact being adapted to connect to an integrated circuit disposed within said inward facing surface.

14. (Original) A package as in claim 13, further comprising an element which seals an inside of said package as compared with an outside.

15. (Original) A package as in claim 14, wherein said element which seals is transparent.

16. (Original) A package as in claim 15, wherein said element is formed of glass, and is hermetically sealed around an area of said inner perimeter.

17. (Previously Presented) A package as in claim 16, further comprising a backing area, hermetically sealing a bottom portion, and wherein said metal contact is disposed around said bottom portion.

18. (New) A support device for an integrated circuit comprising:

a frame member, said frame member having:

a first lateral surface with a first aperture therein;

a second lateral surface disposed in substantially parallel spaced relation to said first lateral surface, said second lateral surface being disposed within said first aperture so as to form a recessed region within said first aperture, said second lateral surface having a second aperture disposed therein, said second aperture being adapted to receive light therethrough; and

an electrical conductor mutually supported by said first lateral surface and said second lateral surface, said electrical conductor being adapted to be coupled to an integrated circuit within said recessed region.

19. (New) A support device for an integrated circuit as defined in claim 18 wherein said integrated circuit comprises a photosensitive device adapted to receive said light.

20. (New) A support device for an integrated circuit as defined in claim 18 further comprising a first medial surface, said first medial surface being disposed between said first and second lateral surfaces and coupling said first and second lateral surfaces within said first aperture.

21. (New) A support device for an integrated circuit as defined in claim 20 wherein said first medial surface is mutually disposed in substantially perpendicular relation to said first and second lateral surfaces respectively.

22. (New) A support device for an integrated circuit as defined in claim 20 wherein said electrical conductor is further supported by said first medial surface.

23. (New) A support device for an integrated circuit as defined in claim 18 wherein said first aperture defines a substantially rectangular perimeter.

24. (New) A support device for an integrated circuit as defined in claim 18 wherein said second aperture defines a substantially rectangular perimeter.

25. (New) A support device for an integrated circuit as defined in claim 18 wherein said electrical conductor is adapted to be coupled to said integrated circuit by a eutectic solder.

26. (New) A support device for an integrated circuit as defined in claim 18 wherein said electrical conductor is adapted to be coupled to said integrated circuit by a wire bond.

27. (New) A support device for an integrated circuit as defined in claim 20 wherein said first aperture defines a first inner perimeter of said first lateral surface and wherein said first lateral surface includes a second outer perimeter; said frame member further including a third lateral surface disposed in substantially parallel spaced relation to said first lateral

surface, said third lateral surface including a third outer perimeter; and

a second medial surface disposed between said first lateral surface and said third lateral surface at said second and third perimeters respectively.

28. (New) A support device for an integrated circuit as defined in claim 27 wherein said second medial surface is disposed in substantially perpendicular relation to said first and third lateral surfaces respectively.

29. (New) A support device for an integrated circuit as defined in claim 28 wherein said electrical conductor is further supported by said second medial surface.

30. (New) A support device for an integrated circuit as defined in claim 27 further comprising a lid member, said lid member having a lid surface.

31. (New) A support device for an integrated circuit as defined in claim 30 wherein said first lateral surface is adapted to support said lid surface.

32. (New) A support device for an integrated circuit as defined in claim 30 wherein said lid member is adapted to be hermetically sealed to said frame member.

33. (New) A support device for an integrated circuit as defined in claim 27 further comprising a lens mount portion said lens mount portion being disposed proximal to said third lateral surface.

34. (New) A support device for an integrated circuit as defined in claim 33 wherein said lens mount portion comprises a lens support feature.

35. (New) A support device for an integrated circuit as defined in claim 34 wherein said lens support feature comprises a helical thread.

36. (New) A support device for an integrated circuit as defined in claim 34 wherein said lens support feature is adapted to allow repositioning of a lens, whereby

said light may be focused through said lens on a photosensitive surface of said integrated circuit.

37. (New) A support device for an integrated circuit as defined in claim 27 wherein a perimeter of said integrated circuit is disposed substantially coincident with said first inner perimeter.

38. (New) A support device for an integrated circuit comprising:

a frame member, said frame member having:

a first lateral surface with a first aperture therein;

a second lateral surface disposed in substantially parallel spaced relation to said first lateral surface, said second lateral surface having a second aperture therein, said second lateral surface being disposed within said first aperture so as to form a first recessed region within said first aperture;

a third lateral surface disposed in substantially parallel spaced relation to said first and second lateral surfaces, said third lateral surface being disposed within said second aperture so as to form a second recessed region within said second aperture, said third lateral surface having a third aperture therein, said third aperture being adapted to receive light therethrough; and

an electrical conductor mutually supported by said first, second and third lateral surfaces said electrical conductor being adapted to be coupled to an integrated circuit within said second recessed region.

39. (New) A support device for an integrated circuit as defined in claim 38 further comprising a back member disposed within said first recessed region.

40. (New) A support device for an integrated circuit as defined in claim 39 wherein said back member is hermetically sealed to said frame member.

41. (New) A support device for an integrated circuit as defined in claim 38 wherein said integrated circuit comprises a photosensitive device adapted to receive said light.

42. (New) A support device for an integrated circuit as defined in claim 38 further comprising a first medial surface, said first medial surface being disposed between said second and third lateral surfaces and coupling said second and third lateral surfaces within said second aperture.

43. (New) A support device for an integrated circuit as defined in claim 42 wherein said first medial surface is mutually disposed in substantially perpendicular relation to said second and third lateral surfaces respectively.

44. (New) A support device for an integrated circuit as defined in claim 42 wherein said electrical conductor is further supported by said second medial surface.

45. (New) A support device for an integrated circuit as defined in claim 38 wherein said second aperture defines a substantially rectangular perimeter.

46. (New) A support device for an integrated circuit as defined in claim 38 wherein said third aperture defines a substantially rectangular perimeter.

47. (New) A support device for an integrated circuit as defined in claim 38 wherein said electrical conductor is adapted to be coupled to said integrated circuit by a eutectic solder.

48. (New) A support device for an integrated circuit as defined in claim 38 wherein said electrical conductor is adapted to be coupled to said integrated circuit by a wire bond.

49. (New) A support device for an integrated circuit as defined in claim 42 wherein said first aperture defines a first inner perimeter of said first lateral surface and wherein said first lateral surface includes a second outer perimeter; said frame member further including a fourth lateral surface disposed in substantially parallel spaced relation to said first lateral surface, said fourth lateral surface including a third outer perimeter; and

a second medial surface disposed between said first lateral surface and said third lateral surface at said second and third perimeters respectively.

50. (New) A support device for an integrated circuit as defined in claim 49 wherein said second medial surface is disposed in substantially perpendicular relation to said first and fourth lateral surfaces respectively.

51. (New) A support device for an integrated circuit as defined in claim 50 wherein said electrical conductor is further supported by said second medial surface.

52. (New) A support device for an integrated circuit as defined in claim 49 further comprising a lid member, said lid member having a lid surface

53. (New) A support device for an integrated circuit as defined in claim 52 wherein said second lateral surface is adapted to support said lid surface.

54. (New) A support device for an integrated circuit as defined in claim 52 wherein said lid member is adapted to be hermetically sealed to said frame member.



55. (New) A support device for an integrated circuit as defined in claim 52 further comprising a lens mount portion said lens mount portion being disposed proximal to said fourth lateral surface.

56. (New) A support device for an integrated circuit as defined in claim 55 wherein said lens mount portion comprises a lens support feature.

57. (New) A support device for an integrated circuit as defined in claim 19 wherein said lens support feature comprises a helical thread.

58. (New) A support device for an integrated circuit as defined in claim 19 wherein said lens support feature is adapted to allow repositioning of a lens, whereby said light may be focused through said lens on a photosensitive surface of said integrated circuit.

59. (New) A support device for an integrated circuit as defined in claim 12 wherein said second aperture defines a fourth inner perimeter and wherein a perimeter of said integrated circuit is adapted to be disposed substantially coincident with said fourth inner perimeter.